

N28HPC Sign-off Methodology and Recommendations

DFD/DMKD

Revision History

Date	Description
2014/04/08	First version
2014/04/17	Add 9T OCV and guideline of mixed 9T & 7T design
2014/05/21	Update the hold-uncertainty with N28HPC model Add mix-OCV/SBOCV guideline
2014/06/05	Redesigned methodology based on flattened blocks; reduced margin required for mixing blocks with cells of different track heights
2014/06/23	Revised FF corner derating with relaxed methodology Enforce derating also on hardened macro
2014/09/30	Revise OCV values based on OCV calculator Add description of OCV calculator Add description of Spatial variation Add description of SBOCV variation components Update hold-uncertainty of SBOCV flow Revise the margin method of 7T/9T interface Revise the demo-case of mix-corner

Revision History

Date	Description
2014/10/08	Revise the technology-migration ratio. Ori: 0.7(early) / 1.0(late). Update: 0.7(early) / 0.9(late)
2014/12/12	Revise recommend OCV values Revise SBOCV IR drop spec Add wire OCV Remove 7T/9T interface margin
2015/01/08	Revise description of OCV customization
2015/01/23	Revise description of wire SBOCV
2015/03/30	Revise description of OCV customization
2015/09/15	Revise the example at page 22 Remove mix block page
2015/09/25	Revise hold margin for U/HVT flops to eliminate characterization inaccuracies caused by flop's internal glitch

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N28HPC Sign-off Methodology Update

- Use global corner for slow (SSG) and total corner for fast (FF)
- **Recommend SBOCV-based sign-off to maximize timing gains**
 - Flat OCV provided here for reference in APR and margin adjustments for mixed HPC/HPM sign-off

Corner	Original	Update
Performance corner	Total corner SS+OCV or SS+SBOCV OCV: Fixed setup margin to cover shorter stage SBOCV: setup margin = clock jitter	Global corner SSG+OCV or SSG+SBOCV OCV: Fixed setup margin to cover shorter stage SBOCV: Setup margin = clock jitter
Hold corner	Faster corner hold: FF+OCV or FF+SBOCV Slower corner hold: SS+OCV or SS+SBOCV OCV: Fixed hold margin to cover shorter stage SBOCV: Hold constraint variation margin per PVT corner	Faster corner hold (same): FF+OCV or FF+SBOCV Slower corner hold : SSG+OCV or SSG+SBOCV OCV: Hold constraint variation margin per PVT corner SBOCV: Hold constraint variation margin per PVT corner

Default OCV Generation Assumptions

- PVT corner: SSG_0.81v_m40c & FF_0p99v_m40c
- Clock cell: CKND2BWP7T30P140 (7T)
- Max clock slew at SSG_0.81_m40C: 200ps
- Data cell: INVD1BWP7T30P140 (7T)
- Max data slew at SSG_0.81v_m40C: 350ps
- IR drop (VDD-VSS variation) : **+/-2.5% for SSG, +/-5% for FF**
- **[NOTE!] Applying default OCV on looser design spec may cause design risk**
 - EX: lower voltage corner, smaller cell, larger slew, larger IR drop
 - Please consult DFD for OCV customization support

N28HPC Chip Sign-Off Corners

Timing Check	Library PVT Conditions	RC Corner	OCV and Design Margin
Setup	SSG/0.81/125C	Cworst	(1a) SBOCV on launch+data /capture clock (1b) Clock jitter
		Rcworst	OR
	SSG/0.81/-40C**	Cworst	(2a) +3.9% on launch clock cell, +7.7% on data clock cell
		Rcworst	and -3.9% on capture cell (2b) -8.5% on capture net (2c) Clock jitter + 25ps setup margin
Hold	SSG/0.81/125C	Cworst	(1a) SBOCV on launch+data/capture clock
		Rcworst	(1b) Flop hold constraint variation margin
	SSG/0.81/-40C**	Cworst	OR
		Rcworst	(2a) -4.9% on launch clock cell, -12.7% on data cell and +4.9% on capture cell (2b) -8.5% on launch clock net, -8.5% on data net (2c) 70ps hold margin
	FF/0.99/125C	Cworst	(1a) SBOCV on capture clock
		Rcworst	(1b) Flop hold constraint variation margin per PVT
	FF/0.99/-40C**	Cworst	OR
		Rcworst	(2a) +13.9% on capture cell (2b) -8.5% on launch clock net, -8.5% on data net (2c) 50ps hold margin
	FF/0.99/125C	Cbest	(1a) SBOCV on capture clock
		Rcbest	(1b) Flop hold constraint variation margin per PVT
	FF/0.99/-40C**	Cbest	OR
		Rcbest	(2a) +13.9% on capture cell (2b) +8.5% on capture net (2c) 50ps hold margin

•Based on TSMC internal experiences on N28HPC 100a library & **v1.0_2p1 SPICE** model

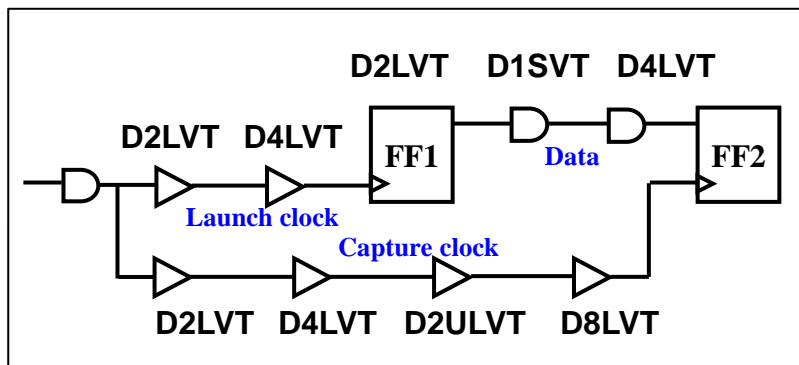
** Low temperature setting (like -40C, -25C, 0C, ...) is design application dependent

OCV Customization

- **TSMC provide OCV customization for customer's design and sign-off conditions**
 - Operating conditions: process, voltage, temperature, slew
 - Variation: IR-drop spec, process sigma
 - Cell library spec: size, V_{th} , gate length, track-height
- **Advise design adjustments to control variation**
 - Eg. use larger-size and lower- V_{th} cells to control the rise in OCV when operating at lower V_{dd}

Always Use Conservative Design Spec in OCV Determination

- Cells with larger variation tend to dominate path variation → should use conservative design spec when determining OCVs
- Use conservative design spec in mixed cell usage
 - The following spec usually result in larger OCV value
 - ◆ Large slew, Large IR_drop, smaller driving strength, lower voltage, slower process, larger Vth
 - But multiple tests on different spec to check which one is more conservative is strongly encouraged

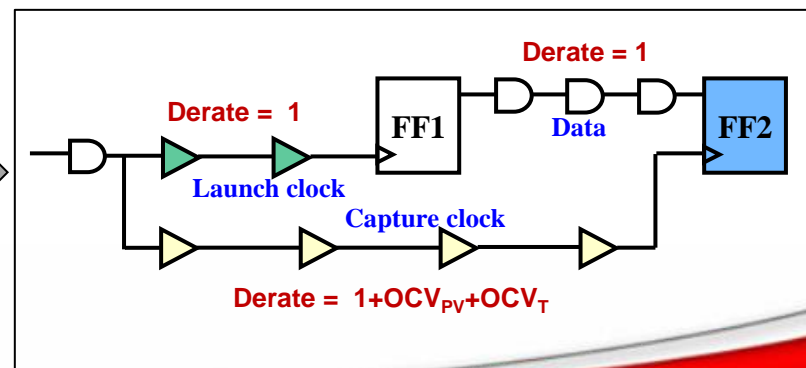
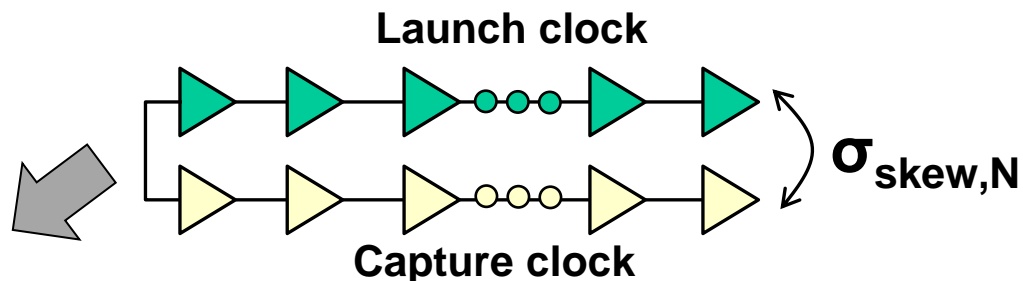
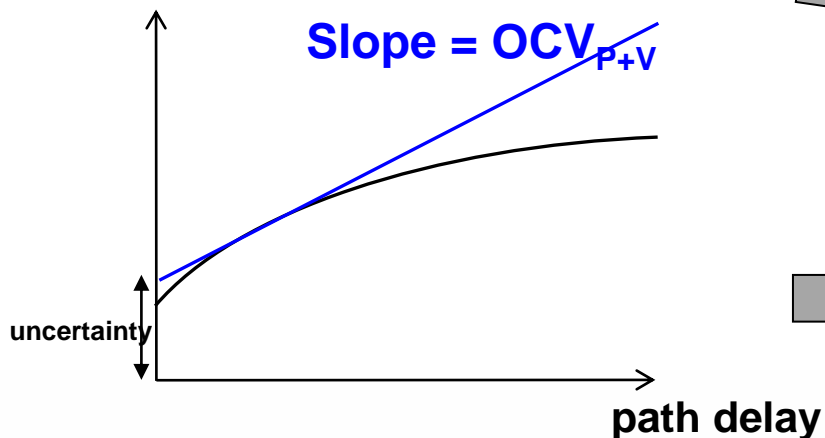


<Recommend spec>
Clock: D2 LVT
Data: D1 SVT

Flat OCV Methodology (FF Corner)

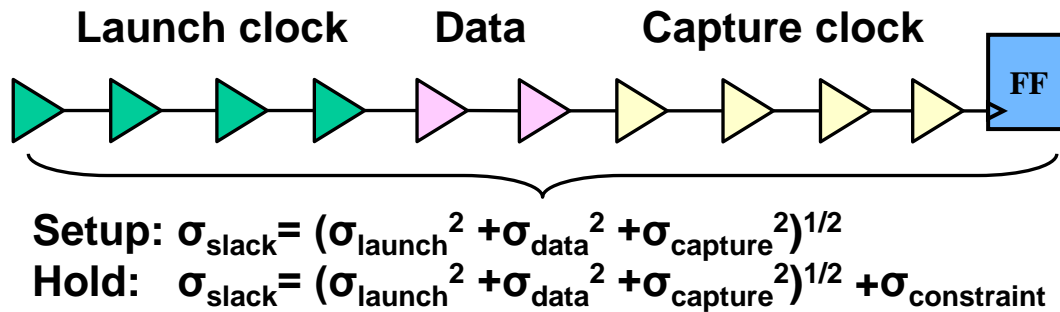
- $OCV = OCV_{P+V} + OCV_{\text{temperature}}$
 - $OCV_{\text{temperature}} = \text{abs}(1 - \text{delay}_{-30C} / \text{delay}_{-40C})$
- $\text{Delay}_{\text{capture}} * OCV + \text{clock_uncertainty} \geq \text{skew variation} + \text{flop variation}$

path variation =
 $3 * (\sigma_{\text{skew},p}^2 + \sigma_{\text{skew},v}^2)^{1/2} + 3 * \sigma_{\text{constraint}}$



Flat OCV Methodology (SSG Corner)

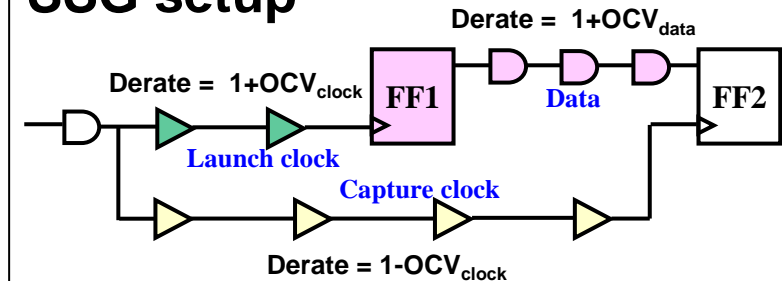
- $\text{delay}_{\text{capture}} * \text{OCV}_{\text{clock}} + \text{delay}_{\text{launch}} * \text{OCV}_{\text{clock}} + \text{delay}_{\text{data}} * \text{OCV}_{\text{data}} + \text{uncertainty} \geq \text{Slack variation}$



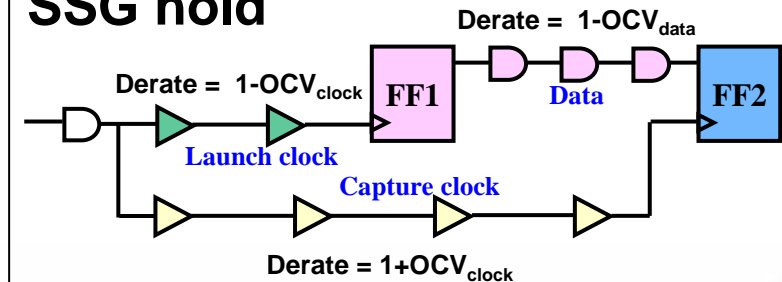
Math solver:

Find $\text{OCV}_{\text{clock}}$ & OCV_{data}
 s.t. $D_{\text{capture}} * \text{OCV}_{\text{clock}} + D_{\text{launch}} * \text{OCV}_{\text{clock}} + D_{\text{data}} * \text{OCV}_{\text{data}} + \text{uncertainty} \geq 3 * \sigma_{\text{slack}}$

SSG setup



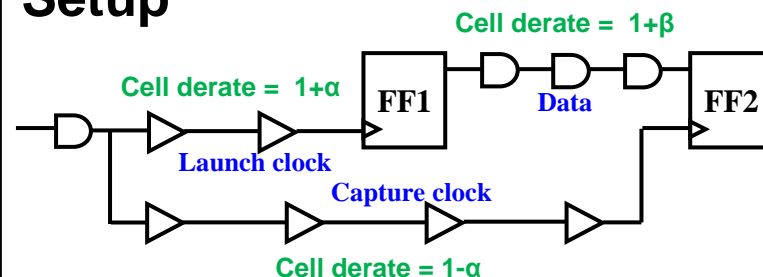
SSG hold



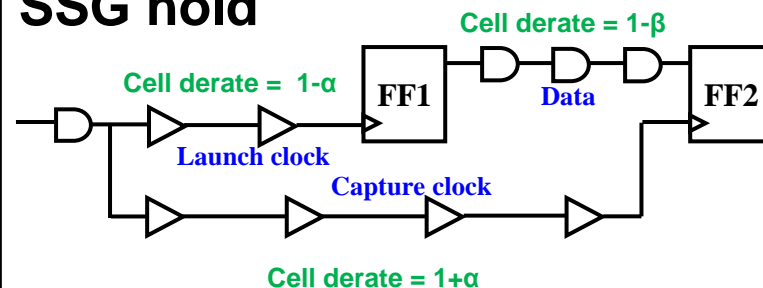
Flat OCV Application

- Apply on both side because library delay is at average(global) delay
- OCV (fitted by global OCV method)
 - Setup (SSG)
 - ◆ [STA] set_timing_derate -late -cell -clock ($1+\alpha$)
 - ◆ [STA] set_timing_derate -late -cell -data ($1+\beta$)
 - ◆ [STA] set_timing_derate -early -cell ($1-\alpha$)
 - Hold (SSG)
 - ◆ [STA] set_timing_derate -early -cell -clock ($1-\alpha$)
 - ◆ [STA] set_timing_derate -early -cell -data ($1-\beta$)
 - ◆ [STA] set_timing_derate -late -cell ($1+\alpha$)
 - Hold (FF)
 - ◆ [STA] set_timing_derate -late -cell ($1+\alpha$)

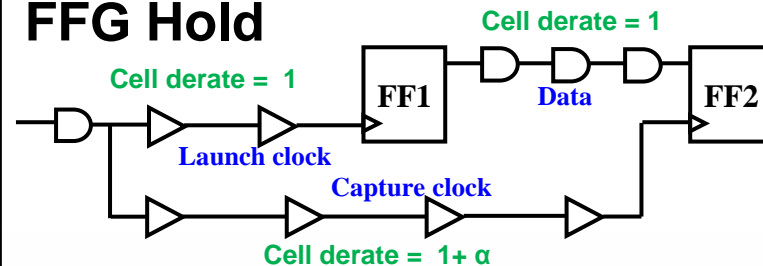
Setup



SSG hold



FFG Hold



ps: $\alpha, \beta, \gamma \geq 0$, stand for clock/data OCV values

Wire OCV Application for Total-RC corner

- Apply wire OCV on one side because another side is already fastest/slowest

- Setup (Cworst/RCworst)

- ◆ [STA] set_timing_derate -late -net -clock 1
- ◆ [STA] set_timing_derate -late -net -data 1
- ◆ [STA] set_timing_derate -early -net (1-8.5%)

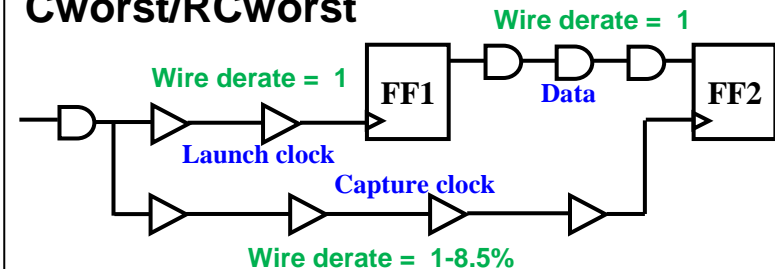
- Hold (Cworst/RCworst)

- ◆ [STA] set_timing_derate -early -net -clock (1-8.5%)
- ◆ [STA] set_timing_derate -early -net -data (1-8.5%)
- ◆ [STA] set_timing_derate -late -net 1

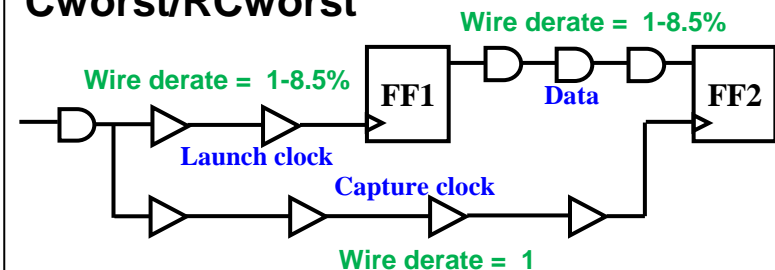
- Hold (Cbest/RCbest)

- ◆ [STA] set_timing_derate -early -net -clock 1
- ◆ [STA] set_timing_derate -early -net -data 1
- ◆ [STA] set_timing_derate -late -net (1+8.5%)

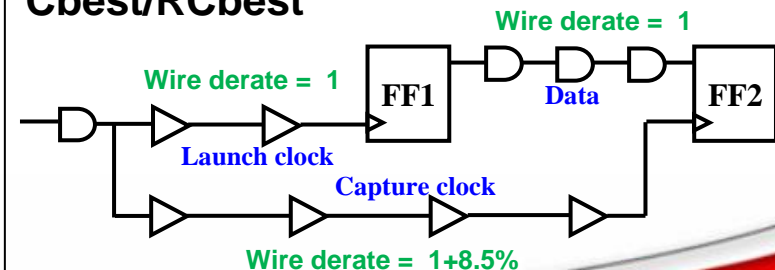
Setup for Cworst/RCworst



Hold for Cworst/RCworst

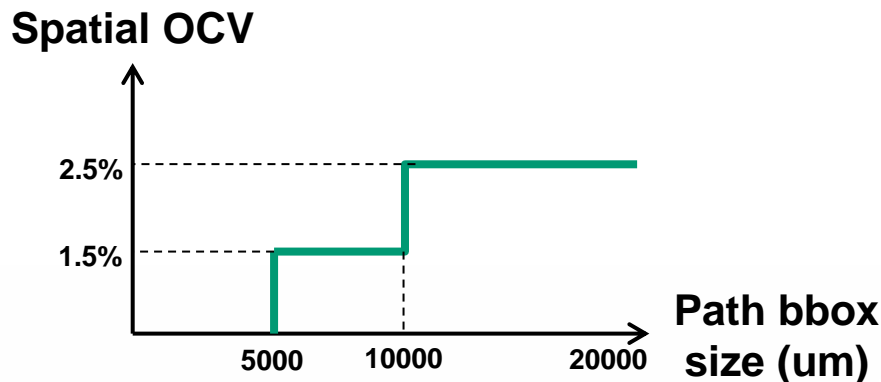


Hold for Cbest/RCbest



Spatial Variation Margin (if applicable)

- Spatial variation margin is added to flat-OCV or SBOCV when diagonal of bounding box encompass the timing path is larger than 5000um
 - SSG early: $(OCV_{\text{early}} \text{ or } SBOCV) - \frac{1}{2} * OCV_{\text{spatial}}$
 - SSG late: $(OCV_{\text{late}} \text{ or } SBOCV) + \frac{1}{2} * OCV_{\text{spatial}}$
 - FF late: $(OCV_{\text{late}} \text{ or } SBOCV) + OCV_{\text{spatial}}$
- EX: For a path contain all 9T cells in SSG corner, bbox diagonal = 6000um, in setup check
 - SSG capture clock derate = $-3.9\% - \frac{1}{2} * 1.5\% = -4.65\%$
 - SSG launch clock derate = $+3.9\% + \frac{1}{2} * 1.5\% = 4.65\%$
 - SSG data derate = $7.7\% + \frac{1}{2} * 1.5\% = 8.45\%$



SBOCV Signoff

SBOCV Variation Component

- **SBOCV should cover at least these independent sources**
 - **FEOL: delay variation by Monte Carlo simulation at global corner**
 - ◆ TSMC apply additional LDE factor multiplied to FEOL variation to account for local layout variation
 - **BEOL: delay variation from wire Res. & Cap. Variation**
 - ◆ TSMC provide wire SBOCV table, please contact FTS
 - **V: delay variation from VDD & VSS variation**
 - **T: delay variation due to temperature difference between launch/capture paths**
- **Customers/designers shall determine their margin for PVT**

TSMC's SBOCV	FEOL	BEOL	V	T
Margin assumption	$3\sigma \cdot \text{LDE}^\dagger$	$\pm 3\sigma_R$ & $\pm 3\sigma_C$	Slow corner: $\pm 2.5\%$ Fast corner: $\pm 5\%$	10°C
Type	Random (Gaussian)	Flat	Random (Gaussian)	Flat
Applied in	Data, Clock	Data, Clock	Clock	Clock

[†] LDE factor is 1.18 for N28HPC

Wire SBOCV

- TSMC provide 2 stand-alone wire SBOCV tables
 - N28_wire_worstrc.aocvm: Cworst & Rcworst
 - N28_wire_bestrc.aocvm: Cbest & Rcbest
- Read best-RC(worst-RC) wire SBOCV after reading all other tables when signoff under best-RC(worst-RC) corner to overwrite other wire SBOCVs in stdcell tables

Example for worst-RC corner (Cworst & RCworst):

```
read_aocvm xxxxx.aocvm  
read_aocvm xxxxx.aocvm  
read_aocvm ./N28_wire_worstrc.aocvm  
...  
update_timing
```

Example for best-RC corner (Cbest & Rcbest)

```
read_aocvm xxxxx.aocvm  
read_aocvm xxxxx.aocvm  
read_aocvm ./N28_wire_bestrc.aocvm  
...  
update_timing
```

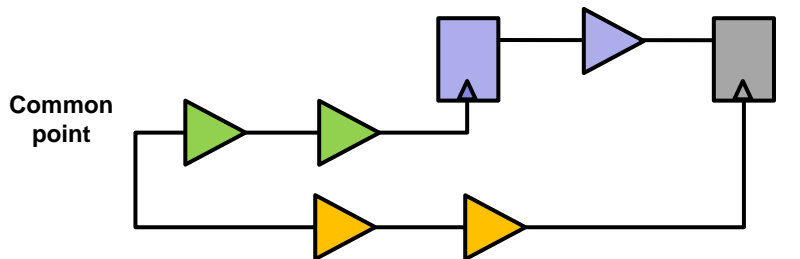
TSMC's SBOCV Deliverable

- TSMC provide 4 types of SBOCV tables based on different scenarios
- Clock_pvt_data_p is recommended for setup & hold analysis
 - Provide other 3 types for customer's specific purpose

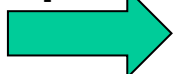
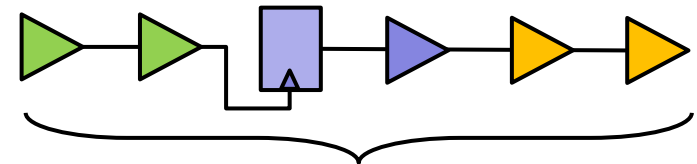
POR SBOCV table type	Variation source in clock path	Variation source in data path
clock_p_data_p	P	P
clock_pvt_data_p	P+V+T	P
clock_pv_data_pv	P+V	P+V
clock_pvt_data_pv	P+V+T	P+V

Global SBOCV Method

- In global corner SBOCV, path slack variation is characterized by a single delay chain consist of capture, launch & data because they are statistically same
 - $\sigma(X-Y) = \sigma(X+Y) = \text{sqrt}(\sigma_X^2 + \sigma_Y^2)$
- Thus user need to lookup SBOCV by total stage of capture, launch & data
- Flat OCV is also generated by same concept



Equal to

$$\text{Slack} = \text{clk_period} + \text{capture} - \text{launch} - \text{data}$$

$$\sigma_{\text{slack}} = \sigma(\text{capture} - \text{launch} - \text{data})$$

$$= \text{sqrt}(\sigma_{\text{capture}}^2 + \sigma_{\text{launch}}^2 + \sigma_{\text{data}}^2)$$

$$\text{Delay} = \text{capture} + \text{launch} + \text{data}$$

$$\sigma(\text{capture} + \text{launch} + \text{data})$$

$$= \text{sqrt}(\sigma_{\text{capture}}^2 + \sigma_{\text{launch}}^2 + \sigma_{\text{data}}^2)$$

$$\text{Derate} = 3\sigma_{\text{slack}} / (\mu_{\text{capture}} + \mu_{\text{launch}} + \mu_{\text{data}})$$

SBOCV Register Constraint Uncertainty

- Setup time uncertainty
 - Margin = clock jitter
- Hold time uncertainty
 - Consider the process variation impact to capture flop
 - Margin = register constraint variation (D & SI uncertainty are separate in below table)

N28HPC CP->D / CP-> SI hold uncertainty (ps)	9T ff0p99v	7T ff0p99v	9T ssg0p81v	7T ssg0p81v
Clk slew	<120ps		<200ps	
D & SI slew	<220ps		<350ps	
ULVT	17/25	24/25	36/53	53/54
LVT	17/26	25/26	41/57	56/58
SVT	19/28	27/28	43/64	60/65
HVT	23/31	31/32	48/90	77/91
UHVT	28/32	33/34	63/142	120/135

- a. Based on simulation with TSMC 28HPC v1d0_2p1 SPICE model & 100a LPE netlist for 9T & 7T SDFQD1
- b. Uncertainty is calculated by 3σ . σ is the constraint variation due to local-process variation.
- c. Lower voltage corner & larger pin slew needs larger uncertainty to cover variation

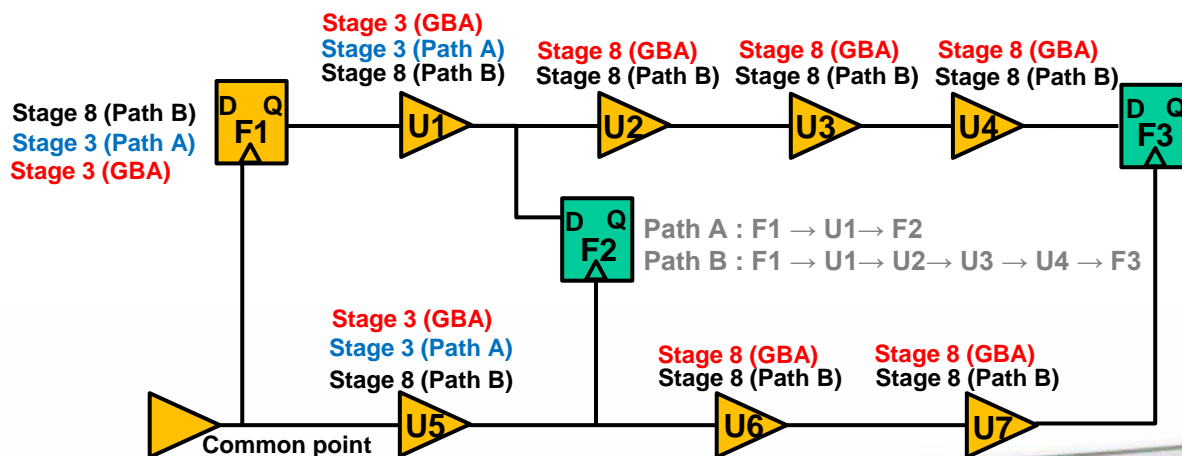
Hold-Constraint Uncertainty in STA

- Hold uncertainty can be set by either way
 1. Insert into hold-constraint table of .lib (Please contact TSMC for the script)
 2. Use SDC command in tool
 - ◆ Ex: `set_clock_uncertainty -hold 0.051 [get_pins -of [get_cells -hier -filter "ref_name =~ *ULVT*"] -filter "is_clock_pin == true"]`
 - ◆ Note!! Cell & pin based uncertainty will be overwritten by inter-clock uncertainty

SBOCV STA Settings

	PrimeTime (v13.12-SP3-1 or after)	Tempus (14.1 or after)
Enable SBOCV analysis	set timing_aocvm_enable_analysis true	set_analysis_mode -aocv true - analysisType onChipVariation -cpr both
Stage counting mode for SSG	set timing_aocvm_analysis_mode combined_launch_capture_depth	set_global timing_aocv_analysis_mode combine_launch_capture
Stage counting mode for FF	set timing_aocvm_analysis_mode separate_data_clock_metrics	set_global timing_aocv_analysis_mode separate_data_clock
PBA timing report	report_timing -pba_mode path	report_timing -retime aocv_path_slew_propagation

- **Must use PBA reporting for SBOCV derate**
 - Using GBA in report_timing will result in very pessimistic derating due to GBA's worst-case stage counting



**PBA vs GBA stage counting
on Path B (from F1 to F3)**

Inst	PBA	GBA
F1	8	3
U1	8	3
U2	8	8
U3	8	8
U4	8	8
U5	8	3
U6	8	8
U7	8	8

* Stage counting in this example is using combine_launch_capture mode

SBOCV ICC Setting

- **Command to analyze SBOCV in ICC**
 - ***set timing_aocvm_enable_analysis true***
 - ***set timing_aocvm_analysis_mode separate_data_and_clock_metrics****
 - ***read_aocvm <sbocv_file>***
 - ***set_fast_pba_analysis_options -num_endpoints 1000***
 - ***apply_fast_pba_analysis***
 - **Fast PBA supported after ICC 2013.03-SP4**

*There is currently no support for combined clock and data stage counting; timing may be pessimistic

SBOCV EDI Setting

- Create “library set” with corresponding SBOCV table
 - *create_library_set -name LIB1 -timing {LIB1.lib} -aocv {LIB1.aocvm}*
- Enable SBOCV analysis before optimization
 - *setAnalysisMode -aocv true*
 - *set_global timing_aocv_analysis_mode separate_data_clock**
 - *set_global timing_enable_aocv_slack_based true*
 - *set_global timing_aocv_slack_threshold 0.0*
 - Slack-based AOCV supported after EDI 13.20–b060

*There is currently no support for combined clock and data stage counting; timing may be pessimistic